

STRUCTURE	Silicon monolithic integrated circuits
PRODUCT SERIES	Bipolar stepping motor driver
TYPE	BD63801EFV
FUNCTION	PWM constant current controllable

two H bridge driver

- Built-in translator circuit for CLK-IN control
- Full, Half step

OAbsolute maximum ratings(Ta=25°C)

Item	Symbol	Limit	Unit
Supply voltage	V _{CC,1,2}	-0.2~+36.0	V
Dewer dissinction		1.1 ^{**1}	W
Power dissipation	Pd	4.0 ^{**2}	W
Input voltage for control pin	V _{IN}	-0.2~+5.5	V
RNF maximum voltage	V _{RNF}	0.5	V
Maximum output current	lout	0.8 ^{**3}	A/phase
Operating temperature range	T _{opr}	-25~+85	°C
Storage temperature range	T _{stg}	-55~+150	°C
Junction temperature	T _{jmax}	+150	°C

^{**1} 70mm × 70mm × 1.6mm glass epoxy board. Derating in done at 8.8mW/°C for operating above Ta=25°C.

^{**2} 4-layer recommended board. Derating in done at 32.0mW/°C for operating above Ta=25°C.

^{**3} Do not, however exceed Pd, ASO and Tjmax=150°C.

ORecommended operating conditions (Ta=-25~+85°C)

Item	Symbol	Min.	Тур.	Max.	Unit
Supply voltage	V _{CC,1,2}	19	24	28	V
Output current	l _{оит}	-	0.3	0.5 ^{%4}	A/phase

^{**4} Do not, however exceed Pd, ASO.

This product isn't designed for protection against radioactive rays.

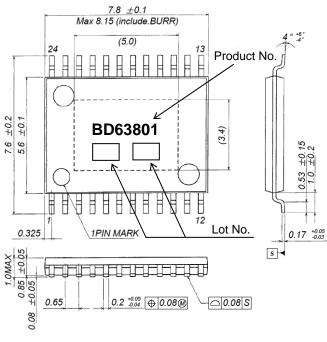


OElectrical characteristics (Unless otherwise specified Ta=25°C, VCC1,2=24V)

			Lincit			
Item	Symbol	Limit			Unit	Conditions
		Min.	Тур.	Max.	Orme	
Whole						
Circuit current at standby	ICCST	-	0.6	2.0	mA	PS=L
Circuit current	Icc	-	2.7	7.0	mA	PS=H, VREFX=0.4V
Control input (IN1A, IN1B, IN2A	, IN2B, PS)					
H level input voltage	V _{INH}	2.0	-	-	V	
L level input voltage	VINL	-	-	0.8	V	
H level input current	I _{INH}	-	33	55	μA	V _{IN} =3.3V
Output (OUT1A, OUT1B, OUT2A	, OUT2B)					
	P		0.0		0	I _{OUT} =0.3A,
Output ON resistance	R _{ON}	-	2.8	3.6	Ω	Sum of upper and lower
Output leak current	I _{LEAK}	-	-	10	μA	
Current control						
RNFX input current	I _{RNF}	-40	-20	-	μA	RNFX=0V
VREFX input current	IVREF	-2.0	-0.1	-	μA	VREFX=0V
VREFX input voltage range	V _{REF}	0	-	0.4	V	
Comparator offset	V _{COF}	-20	0	20	mV	VREFX=0.4V
Minimum on time	tonmin	0.3	0.7	1.2	μs	R=39kΩ,C=1000pF

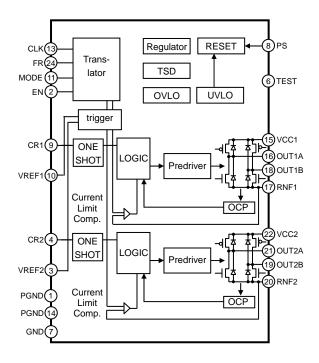


OPackage outline



HTSSOP-B24 (Unit: mm)

OBlock diagram



OPin No. / Pin name

Pin No.	Pin name	Pin No.	Pin name
1	PGND	13	CLK
2	EN	14	PGND
3	VREF2	15	VCC1
4	CR2	16	OUT1A
5	NC	17	RNF1
6	TEST	18	OUT1B
7	GND	19	OUT2B
8	PS	20	RNF2
9	CR1	21	OUT2A
10	VREF1	22	VCC2
11	MODE	23	NC
12	NC	24	FR

NC : Non Connection



OOperation Notes

(1) Absolute maximum ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.

(2) Power supply lines

As return of current regenerated by back EMF of motor happens, take steps such as putting capacitor between power supply and GND as an electric pathway for the regenerated current. Be sure that there is no problem with each property such as emptied capacity at lower temperature regarding electrolytic capacitor to decide capacity value. If the connected power supply does not have sufficient current absorption capacity, regenerative current will cause the voltage on the power supply line to rise, which combined with the product and its peripheral circuitry may exceed the absolute maximum ratings. It is recommended to implement a physical safety measure such as the insertion of a voltage clamp diode between the power supply and GND pins.

(3) GND potential

The potential of GND pin must be minimum potential in all operating conditions.

(4) Metal on the backside (Define the side where product markings are printed as front) The metal on the backside is shorted with the backside of IC chip therefore it should be connected to GND. Be aware that there is a possibility of malfunction or destruction if it is shorted with any potential other than

GND.

(5) Thermal design

Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions. This IC exposes its frame of the backside of package. Note that this part is assumed to use after providing heat dissipation treatment to improve heat dissipation efficiency. Try to occupy as wide as possible with heat dissipation pattern not only on the board surface but also the backside.

(6) Actions in strong electromagnetic field

Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.

(7) ASO

When using the IC, set the output transistor so that it does not exceed absolute maximum ratings or ASO. (8) Thermal shutdown circuit

The IC has a built-in thermal shutdown circuit (TSD circuit). If the chip temperature becomes Tjmax=150°C, and higher, coil output to the motor will be open. The TSD circuit is designed only to shut the IC off to prevent runaway thermal operation. It is not designed to protect or indemnify peripheral equipment. Do not use the TSD function to protect peripheral equipment.

(9) Ground Wiring Pattern

When using both small signal and large current GND patterns, it is recommended to isolate the two ground patterns, placing a single ground point at the ground potential of application so that the pattern wiring resistance and voltage variations caused by large currents do not cause variations in the small signal ground voltage. Be careful not to change the GND wiring pattern of any external components, either.

(10) Mounting errors and Inter-pin short

When attaching to a printed circuit board, pay attention to the direction of the IC and displacement. Improper attachment may lead to destruction of the IC. There is also possibility of destruction from shortcircuits which can be caused by foreign matter entering between pins.

(11) TEST pin

Be sure to connect TEST pin to GND.

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